# onsemi

# Low On-Resistance, Slew-Rate-Controlled Load Switch

# FPF1038

### Description

The FPF1038 advanced load-management switch target applications requiring a highly integrated solution for disconnecting loads powered from DC power rail (<6 V) with stringent shutdown current targets and high load capacitances (up to 200  $\mu$ F). The FPF1038 consists of slew-rate controlled low-impedance MOSFET switch (21 m $\Omega$  typical) and other integrated analog features. The slew-rate controlled turn-on characteristic prevents inrush current and the resulting excessive voltage droop on power rails.

These devices have exceptionally low shutdown current drain (<1  $\mu$ A maximum) that facilitates compliance in low standby power applications. The input voltage range operates from 1.2 V to 5.5 V DC to support a wide range of applications in consumer, optical, medical, storage, portable, and industrial device power management.

Switch control is managed by a logic input (active HIGH) capable of interfacing directly with low-voltage control signal / GPIO with no external pull-up required. The device is packaged in advanced fully "green" 1 mm x 1.5 mm Wafer-Level Chip-Scale Packaging (WLCSP); providing excellent thermal conductivity, small footprint, and low electrical resistance for wider application usage.

### Features

- 1.2 V to 5.5 V Input Voltage Operating Range
- Typical R<sub>ON</sub>:
  - 20 m $\Omega$  at V<sub>IN</sub> = 5.5 V
  - 21 m $\Omega$  at V<sub>IN</sub> = 4.5 V
  - 37 m $\Omega$  at V<sub>IN</sub> = 1.8 V
  - 75 m $\Omega$  at V<sub>IN</sub> = 1.2 V
- Slew Rate / Inrush Control with t<sub>R</sub>: 2.7 ms (Typical)
- 3.5 A Maximum Continuous Current Capability
- Low <1 µA Shutdown Current
- ESD Protected: Above 8 kV HBM, 1.5 kV CDM
- GPIO / CMOS–Compatible Enable Circuitry
- This Device is Pb-Free, Halide Free and is RoHS Compliant

# Applications

- HDD, Storage, and Solid-State Memory Devices
- Portable Media Devices, UMPC, Tablets, MIDs
- Wireless LAN Cards and Modules
- SLR Digital Cameras
- Portable Medical Devices
- GPS and Navigation Equipment
- Industrial Handheld and Enterprise Equipment



WLCSP6 1.5x1.0x0.582 CASE 567RL

#### MARKING DIAGRAM



QE = Specific Device Code

- &K = 2-Digits Lot Run Traceability Code
- &. = Pin One Dot
- &2 = 2–Digit Date Code
- &Z = Assembly Plant Code

### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 11 of this data sheet.

# **APPLICATION DIAGRAM**

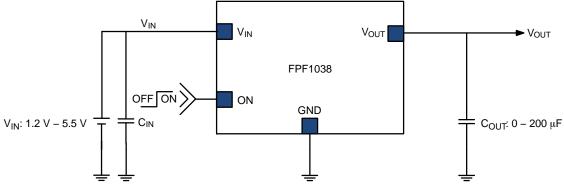


Figure 1. Typical Application

# FUNCTIONAL BLOCK DIAGRAM

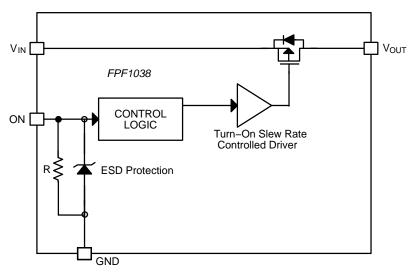


Figure 2. Functional Block Diagram

# **PIN CONFIGURATION**

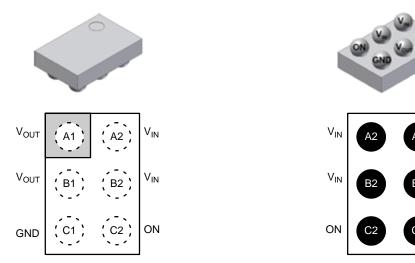
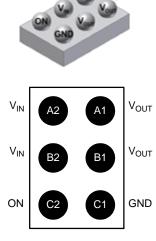


Figure 3. Top View



Pin 1

Figure 4. Bottom View

## **PIN DEFINITIONS**

Pin No.	Name	Description				
A1, B1	V <sub>OUT</sub>	itch Output				
A2, B2	V <sub>IN</sub>	pply Input: Input to the Power Switch				
C1	GND	round				
C2	ON	DN/OFF Control, Active High – GPIO Compatible				

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Paran	Min	Max	Unit
V <sub>IN</sub>	V <sub>IN</sub> , V <sub>OUT</sub> , V <sub>ON</sub> to GND	-0.3	6.0	V
I <sub>SW</sub>	Maximum Continuous Switch Current	-	3.5	А
PD	Power Dissipation at $T_A = 25^{\circ}C$	-	1.2	W
T <sub>STG</sub>	Storage Junction Temperature	-65	+150	°C
T <sub>A</sub>	Operating Temperature Range	-40	+85	°C
$\Theta_{JA}$	Thermal Resistance, Junction-to-Ambie	-	85 (Note 1)	°C/W
		-	110 (Note 2)	
ESD	Electrostatic Discharge Capability	8.0	-	kV
		1.5	-	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Measured using 2S2P JEDEC std. PCB.

2. Measured using 2S2P JEDEC PCB COLD PLATE method.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameters	Min	Max	Unit
V <sub>IN</sub>	Input Voltage	1.2	5.5	V
T <sub>A</sub>	Ambient Operating Temperature	-40	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

**ELECTRICAL CHARACTERISTICS** (Unless otherwise noted,  $V_{IN}$  = 1.2 to 5.5 V and  $T_A$  = -40 to +85°C; typical values are at  $V_{IN}$  = 4.5 V and  $T_A$  = 25°C.)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
BASIC OP	ERATION					
V <sub>IN</sub>	Input Voltage	1.2	-	5.5	V	
I <sub>Q(OFF)</sub>	Off Supply Current	V <sub>ON</sub> = GND, V <sub>OUT</sub> = Open	-	-	1.0	μΑ
I <sub>SD</sub>	Shutdown Current	V <sub>ON</sub> = GND, V <sub>OUT</sub> = GND	-	0.2	1.0	μΑ
Ι <sub>Q</sub>	Quiescent Current	I <sub>OUT</sub> = 0 mA	-	5.5	8.0	μΑ
R <sub>ON</sub>	On Resistance	V <sub>IN</sub> = 5.5 V, I <sub>OUT</sub> = 1 A (Note 3)	-	20	24	mΩ
		$V_{IN} = 4.5 \text{ V}, I_{OUT} = 1 \text{ A}, T_A = 25^{\circ}\text{C}$	-	21	25	1
		V <sub>IN</sub> = 3.3 V, I <sub>OUT</sub> = 500 mA (Note 3)	-	24	29	1
		V <sub>IN</sub> = 2.5 V, I <sub>OUT</sub> = 500 mA (Note 3)	-	28	35	1
		V <sub>IN</sub> = 1.8 V, I <sub>OUT</sub> = 250 mA (Note 3)	-	37	45	1
		$V_{IN}$ = 1.2 V, $I_{OUT}$ = 250 mA, $T_A$ = 25°C	-	75	100	1
V <sub>IH</sub>	On Input Logic HIGH Voltage		1.0	-	-	V
VIL	On Input Logic LOW Voltage		-	-	0.4	V
I <sub>ON</sub>	On Input Leakage		-	-	1.0	μΑ

### DYNAMIC CHARACTERISTICS

t <sub>DON</sub>	Turn-On Delay (Note 4)	$V_{IN} = 4.5 \text{ V}, \text{ R}_{L} = 5 \Omega, \text{ C}_{L} = 100 \mu\text{F},$		1.7	-	ms
t <sub>R</sub>	V <sub>OUT</sub> Rise Time (Note 4)	$T_A = 25^{\circ}C$	-	2.7	-	ms
t <sub>ON</sub>	Turn–On Time (Note 6)		-	4.4	-	ms
t <sub>DOFF</sub>	Turn-Off Delay (Note 4)	$V_{IN} = 4.5 \text{ V}, \text{ R}_{L} = 150 \Omega, \text{ C}_{L} = 100 \mu\text{F},$	-	2.0	-	ms
t <sub>F</sub>	V <sub>OUT</sub> Fall Time (Note 4)	$T_A = 25^{\circ}C$ , No Load Discharge	-	30.0	-	ms
t <sub>OFF</sub>	Turn–Off (Note 7)		-	32.0	-	ms

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics for the listed test conditions. 3. This parameter is guaranteed by design and characterization; not production tested. 4.  $t_{DON}/t_{DOFF}/t_R/t_F$  are defined in Figure 27. 5. Output discharge enabled during off-state.

6.  $t_{OFF} = t_R + t_{DOFF}$ 7.  $t_{OFF} = t_F + t_{DOFF}$ 

# **TYPICAL CHARACTERISTICS**

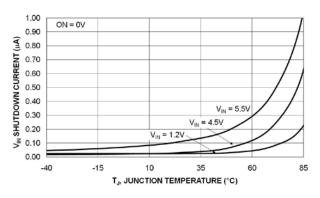


Figure 5. Shutdown Current vs. Temperature

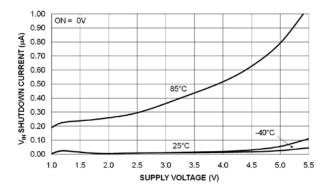


Figure 6. Shutdown Current vs. Supply Voltage

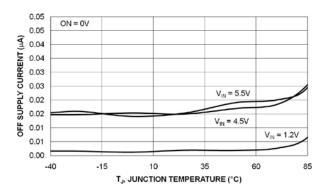


Figure 7. Off Supply Current vs. Temperature (V<sub>OUT</sub> Floating)

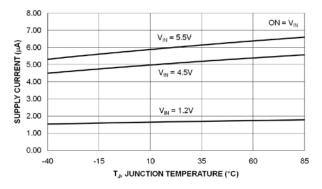


Figure 9. Quiescent Current vs. Temperature

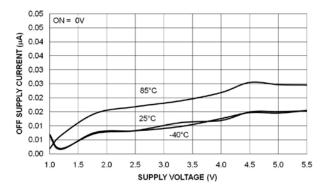


Figure 8. Off Supply Current vs. Supply Voltage (V<sub>OUT</sub> Floating)

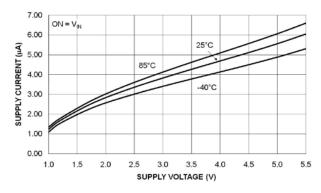
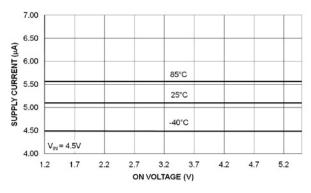
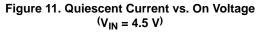


Figure 10. Quiescent Current vs. Supply Voltage

# TYPICAL CHARACTERISTICS (continued)





V<sub>IN</sub> = 1.2 V

V<sub>IN</sub> = 4.5 V

V<sub>IN</sub> = 5.5 V

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

35

10

Figure 13. R<sub>ON</sub> vs. Temperature

-ON = V<sub>IN</sub> \_I<sub>OUT</sub> = 0.25 A @ 1.2 V

I<sub>OUT</sub> = 1 A @ 4.5 V & 5.5 V

60

85

90

80

70

60

50

40

30

20

10 0

-40

-15

ON RESISTANCE (mOhm)

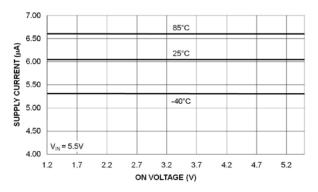


Figure 12. Quiescent Current vs. On Voltage  $({\rm V_{IN}}=5.5~{\rm V})$ 

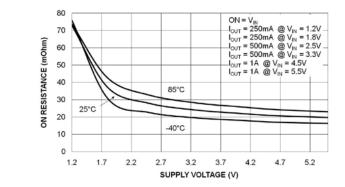


Figure 14. R<sub>ON</sub> vs. Supply Voltage

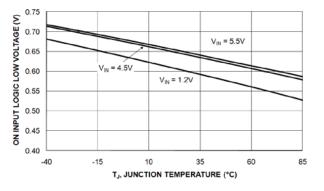


Figure 15. On Pin Threshold Low vs. Temperature

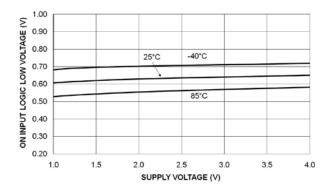


Figure 16. On Pin Threshold Low vs.  $\rm V_{IN}$ 

# TYPICAL CHARACTERISTICS (continued)

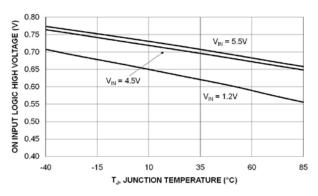


Figure 17. On Pin Threshold High vs. Temperature

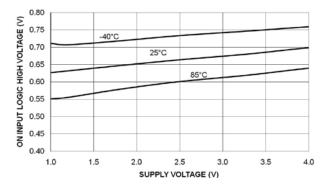


Figure 18. On Pin Threshold High vs. VIN

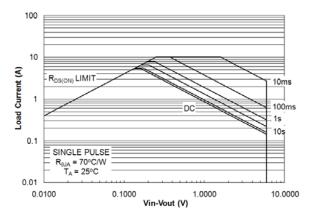


Figure 20. I<sub>SW</sub> vs. (V<sub>IN</sub>-V<sub>OUT</sub>) — SOA

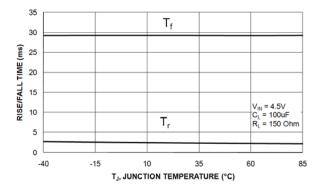


Figure 22. t<sub>R</sub>/t<sub>F</sub> vs. Temperature

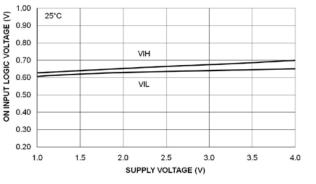
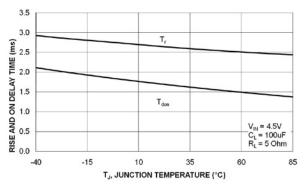


Figure 19. On Pin Threshold vs. Supply Voltage





## TYPICAL CHARACTERISTICS (continued)

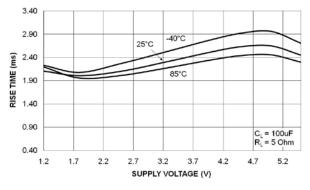


Figure 23. t<sub>R</sub> vs. Supply Voltage

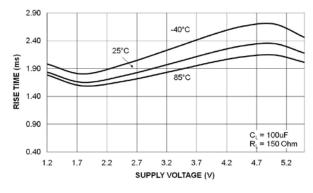
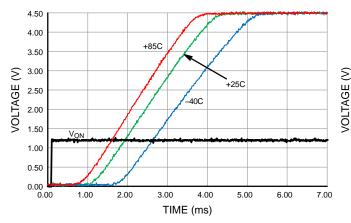


Figure 24. t<sub>R</sub> vs. Supply Voltage



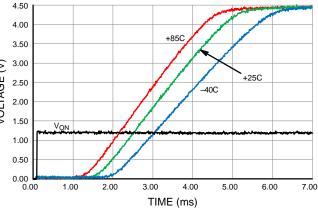


Figure 25. Turn–On Response (V<sub>IN</sub> = 4.5 V, C<sub>IN</sub> = 10  $\mu$ F, C<sub>L</sub> = 1  $\mu$ F, R<sub>L</sub> = 50  $\Omega$ )

Figure 26. Turn–On Response (V<sub>IN</sub> = 4.5 V, C<sub>IN</sub> = 10  $\mu$ F, C<sub>L</sub> = 100  $\mu$ F, R<sub>L</sub> = 5  $\Omega$ )

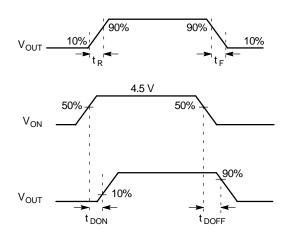


Figure 27. Timing Diagram

#### APPLICATION INFORMATION

#### Input Capacitor

This IntelliMAX<sup>TM</sup> switch doesn't require an input capacitor. To reduce device inrush current, a 0.1  $\mu$ F ceramic capacitor, C<sub>IN</sub>, is recommended close to the VIN pin. A higher value of C<sub>IN</sub> can be used to reduce the voltage drop experienced as the switch is turned on into a large capacitive load.

#### **Output Capacitor**

While this switch works without an output capacitor: if parasitic board inductance forces  $V_{OUT}$  below GND when switching off; a 0.1  $\mu$ F capacitor,  $C_{OUT}$ , should be placed between  $V_{OUT}$  and GND.

#### Fall Time

Device output fall time can be calculated based on RC constant of the external components as follows:

$$t_{\rm F} = R_{\rm L} \times C_{\rm L} \times 2.2 \tag{eq. 1}$$

where  $t_F$  is 90% to 10% fall time,  $R_L$  is output load, and  $C_L$  is output capacitor.

The same equation works for a device with a pull-down output resistor.  $R_L$  is replaced by a parallel connected pull-down and an external output resistor combination as:

$$t_{F} = \frac{R_{L} \times R_{PD}}{R_{L} + R_{PD}} \times C_{L} \times 2.2 \tag{eq. 2}$$

where  $t_F$  is 90% to 10% fall time,  $R_L$  is output load,  $R_{PD} = 65 \Omega$  is output pull-down resistor, and  $C_L$  is the output capacitor.

#### **Resistive Output Load**

If resistive output load is missing, the IntelliMAX switch without a pull-down output resistor does not discharge the output voltage. Output voltage drop depends, in that case, mainly on external device leaks.

#### **Application Specifics**

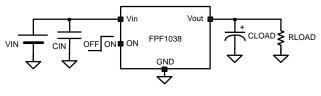


Figure 28. Device Setup

At maximum operational voltage ( $V_{IN} = 5.5$  V), device inrush current might be higher than expected. Spike current should be taken into account if  $V_{IN} > 5$  V and the output capacitor is much larger than the input capacitor. Input current can be calculated as:

$$I_{IN}(t) \approx \frac{V_{OUT}(t)}{R_{LOAD}} + \left(C_{LOAD} - C_{IN}\right) \frac{dV_{OUT}(t)}{dt}$$
 (eq. 3)

where switch and wire resistances are neglected and capacitors are assumed ideal.

Estimating  $V_{OUT}(t) = V_{IN} / 10$  and using experimental formula for slew rate ( $dV_{OUT}(t) / dt$ ), spike current can be written as:

$$max(I_{IN}) = \frac{V_{IN}}{10R_{LOAD}} + (C_{LOAD} - C_{IN})(0.05V_{IN} - 0.255)$$
(eq. 4)

where supply voltage  $V_{\rm IN}$  is in volts, capacitances are in micro farads, and resistance is in ohms.

Example: If  $V_{IN} = 5.5$  V,  $C_{LOAD} = 100 \ \mu\text{F}$ ,  $C_{IN} = 10 \ \mu\text{F}$ , and  $R_{LOAD} = 50 \ \Omega$ ; calculate the spike current by:

$$\max(I_{IN}) = \frac{5.5}{10 \times 50} + (100 - 10)(0.05 \times 5.5 - 0.255) A =$$
  
= 1.8 A (eq. 5)

Maximum spike current is 1.8 A, while average ramp–up current is:

$$I_{IN}(t) \approx \frac{V_{OUT}(t)}{R_{LOAD}} + (C_{LOAD} - C_{IN}) \frac{dV_{IN}(t)}{dt}$$
  
$$\approx 2.75 / 50 + 100 \times 0.0022 = 0.275 \text{ A}$$
(eq. 6)

#### **Recommended Layout**

For best thermal performance and minimal inductance and parasitic effects, it is recommended to keep input and output traces short and capacitors as close to the device as possible. Figure 29 is a recommended layout for this device to achieve optimum performance.

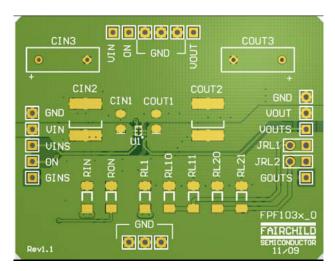


Figure 29. Recommended Land Pattern, Layout

#### **ORDERING INFORMATION**

Part Number	Top Mark	Switch R <sub>ON</sub> (Typical) at 4.5 V <sub>IN</sub>	Input Buffer	Output Discharge	ON Pin Activity	t <sub>R</sub>	Package	Shipping <sup>†</sup>
FPF1038UCX	QE	21 mΩ	CMOS	NA	Active HIGH	2.7 ms	6–Bump, WLCSP, 1.0 mm x 1.5 mm, 0.5 mm Pitch (Pb–Free)	3000 / Tape & Reel

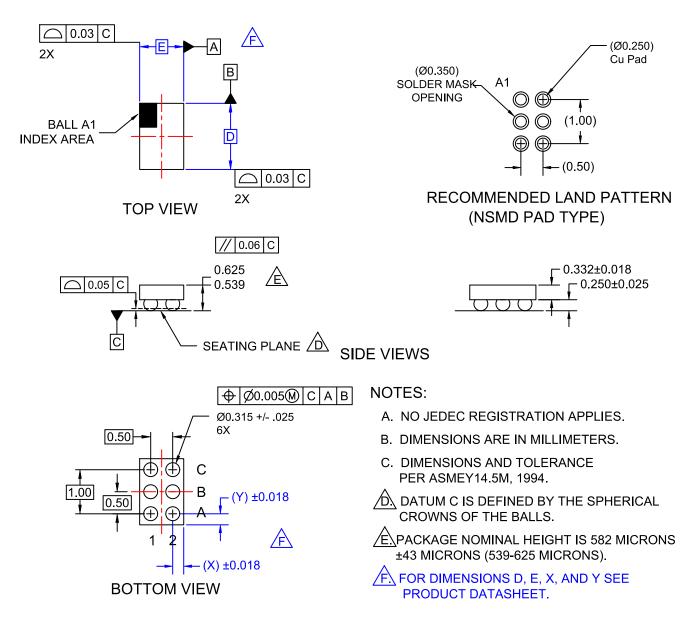
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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WLCSP6 1.5x1.0x0.582 CASE 567RL ISSUE O

DATE 30 NOV 2016



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